Hiner-pack® MVWS Canister 150 mm

Vertical stacking shipper with cassette, bottom, and top for wafer protection

For full-thickness wafer storage and transport, the vertical wafer shipper features a bottom tray, cassette, and top cover in a three-in-one structure. Capable of holding up to 25 wafers, it uses a vertical stacking design to minimize slot movement, protecting wafer edges during shipment. The top section's built-in support springs or alignment keys prevent rotation, vibration, and contact between wafers. Meeting standard cassette footprints, it offers plug-and-play compatibility with load ports, automated transfer robots, and semiconductor wafer storage solutions. Made from high-grade polypropylene, it meets stringent cleanroom requirements with ultra-low ionics and minimal outgassing.

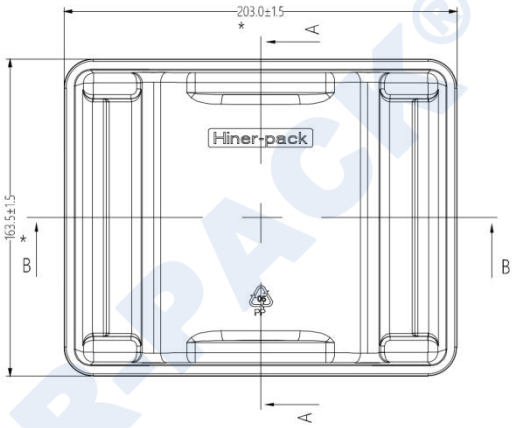
SPECIFICATIONS

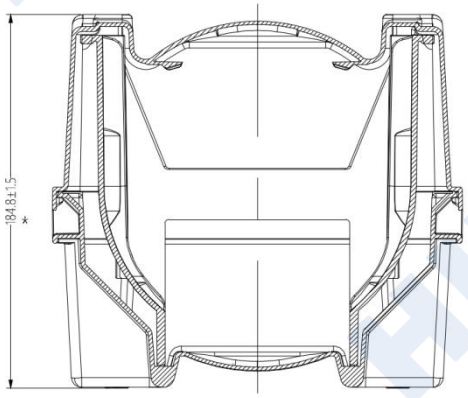
- 203 mm L × 163.5 mm W × 184.8 mm H (7.99" × 6.44" ×7.28")
- Maximum load capacity is 25 pieces
- Sold in full case quantity (18)

FEATURES & BENEFITS

- Made from low-particle/ionic/outgassing material
- Three-piece design includes bottom, cassette, and top
- Springs or alignment features inside the upper cover prevent wafer movement during handling
- Compatible with automation load ports and standard cassette handling tools

DIMENSION





SECTION B-B

BASIC INFORMATION

Part Number	Collocation Reference	Wafer Size
MVWS-6/25-NP-B	Bottom+Cassette+Top	150 mm

REFERENCE ILLUSTRATION

The above illustration is for reference only. Please refer to the actual product for accuracy.

TECHNICAL DATA

PROPERTY	TEST METHOD	RATED VALUES
Density	ISO 1183	0.9 g/cm³
Melt Index	ISO 1133	15 g/10min
Melting Point	DSC	146°C
Distortion Temperature	ISO 75	95°C
Vicat softening temperature	ISO 306	125°C
Tensile Strength at Yield	ISO 527	280 kg/m²
Tensile Elongation at Break	ISO 527	300 %
Rockwell hardness R scale	ISO 2039	98
Tensile Strain at Break	ISO 527-2 (50mm/min)	10 %
Flexural Modulus	ISO 178	10500 kg/m²
Flow Shrinkage	FPC Method	1.3~1.7 %
LZOD Impact Strength	ISO 180 23°C	6 kg.cm/cm
	ISO 180 -20°C	--- notch

The information on technical data included in this document is based on our experience to date, and we believe it to be reliable. Data is obtained from specimens molded under controlled conditions from representative samples of the compound described. Properties may be affected by the molding techniques and by the size and shape of the item molded. We cannot guarantee favorable results and no assurances can be implied that all molded articles have the sample properties as those listed.

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